

Supporting information

Ultrathin CoFe-layered double hydroxide nanosheets embedded in high conductance Cu₃N nanowire arrays with 3D core-shell architecture for ultrahigh capacitance supercapacitor

Xing Zhou, Xiaohui Li, Dejian Chen, Danyang Zhao and Xintang Huang*

Institute of Nanoscience and Nanotechnology, College of Physical Science and Technology, Central China Normal University, Wuhan 430079, China

* Corresponding author. E-mail: xthuang@mail.ccnu.edu.cn

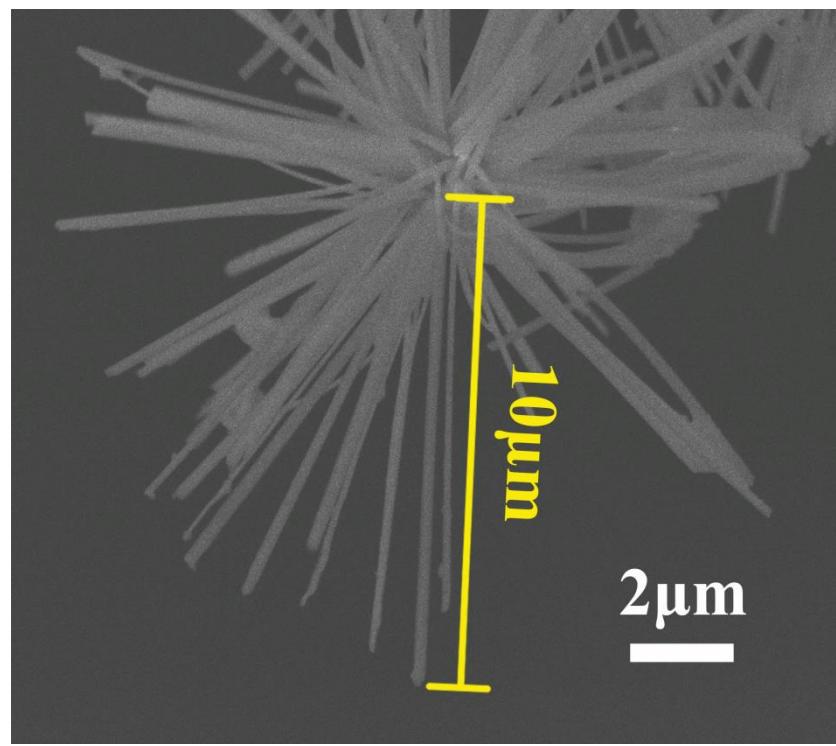


Fig. S1 SEM image of single $\text{Cu}(\text{OH})_2$ nanowire with the length about 10 μm .

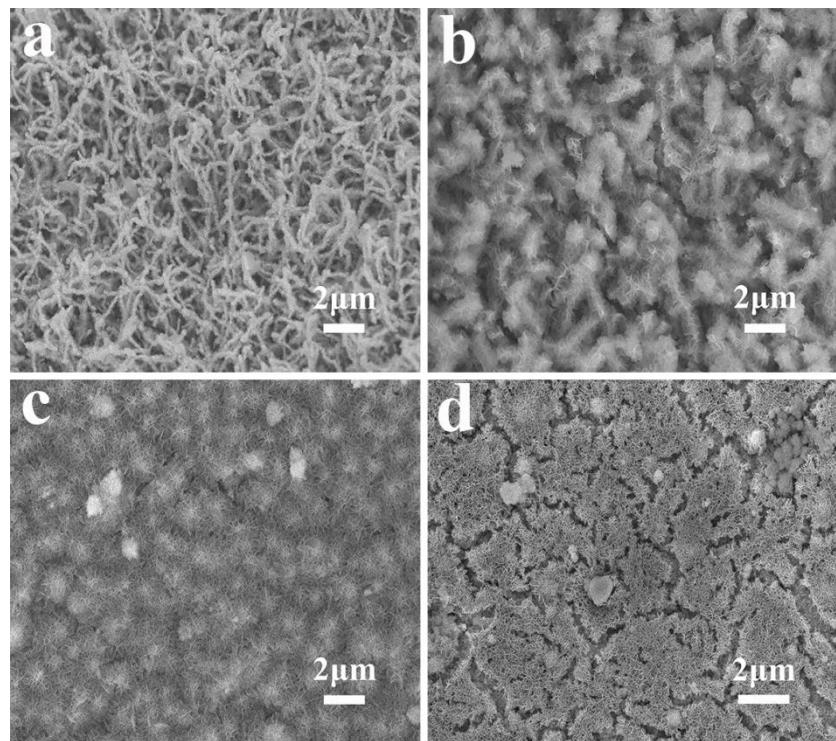


Fig. S2 SEM images of $\text{Cu}_3\text{N}@\text{CoFe-LDH}$ core-shell NWAs synthesized with various LDH electrodeposition time: (a) 25 s, (b) 50 s, (c) 100 s, (d) 200 s, respectively.

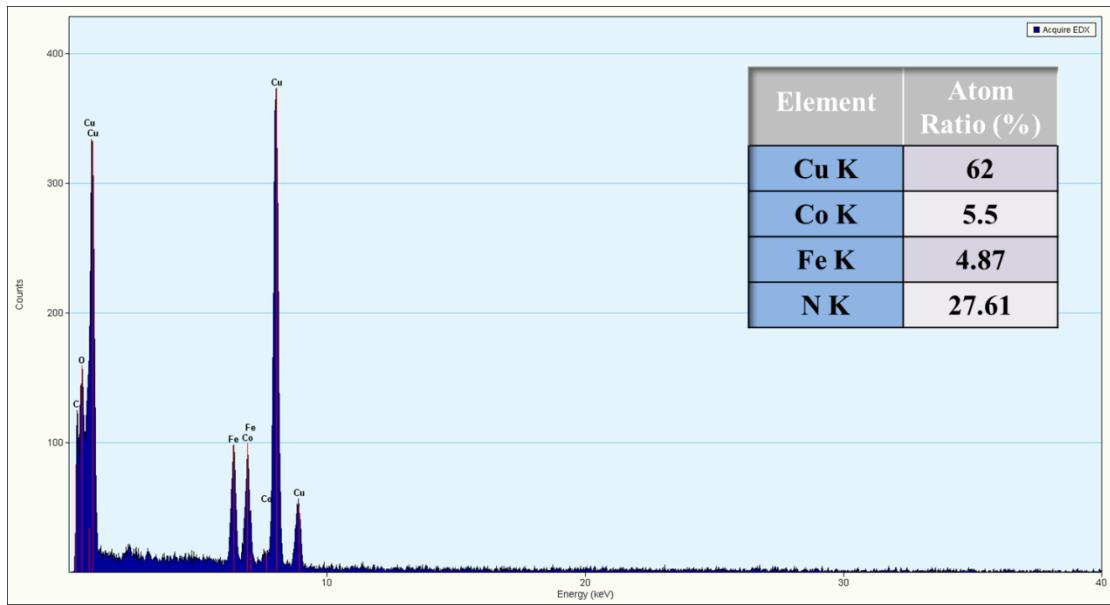


Fig. S3 EDX spectra of the $\text{Cu}_3\text{N}@\text{CoFe-LDH}$ NWAs.

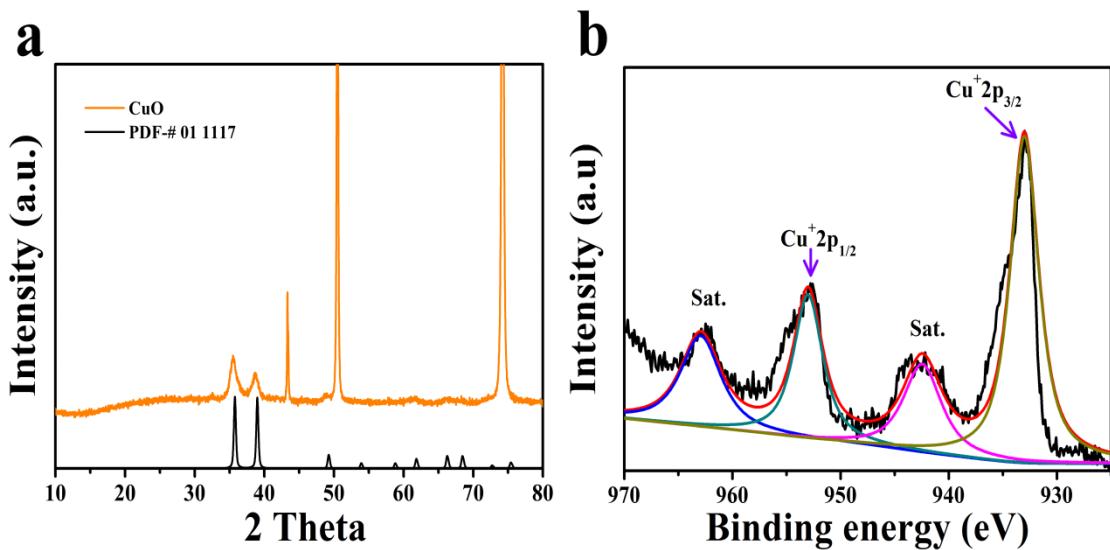


Fig. S4 (a) XRD spectra of CuO NWAs supported on Cu foam substrate; (b) Typical Cu 2p XPS spectra of the $\text{Cu}_3\text{N}@\text{CoFe-LDH}$ NWAs

Table S1. Comparison of the electrochemical performance of Cu₃N@CoFe-LDH NWAs electrode in three-electrode systems with other previously reported electrodes.

Materials	Specific capacitance	Current density	Electrolyte	Retention-cycles	ΔV (V)	Reference (year)
CuO@CoFe-LDH core-shell structures	0.866 F cm ⁻²	1 mA cm ⁻¹	1 M KOH	92.4%-1000	0.45	S1 (2016)
CuCo ₂ O ₄ @Co(OH) ₂ core-shell structures	424 F g ⁻¹	0.5 A g ⁻¹	1 M KOH	85.8%-10000	0.4	S2 (2017)
NiO@CoFe-LDH core-shell structures	361 C g ⁻¹	1 A g ⁻¹	2 M KOH	19.1% - 5000	0.5	S3 (2017)
NiCo ₂ O ₄ @MnO ₂ core-shell structures	2.05 F cm ⁻²	10 mA cm ⁻²	1 M LiOH	88% - 2000	0.6	S4 (2013)
Co ₃ O ₄ @NiO core-shell structures	1.35 F cm ⁻²	6 mA cm ⁻²	2 M KOH	95.1% - 6000	0.55	S5 (2012)
Co _x Ni _{1-x} DHs@NiCo ₂ O ₄ core-shell structures	1.64 F cm ⁻²	2 mA cm ⁻²	1 M KOH	81.3% - 2000	0.55	S6 (2013)
Cu ₃ N@CoFe-LDH core-shell structures	3.08 F cm ⁻²	1 mA cm ⁻²	2 M KOH	93.9% - 10000	0.45	The work

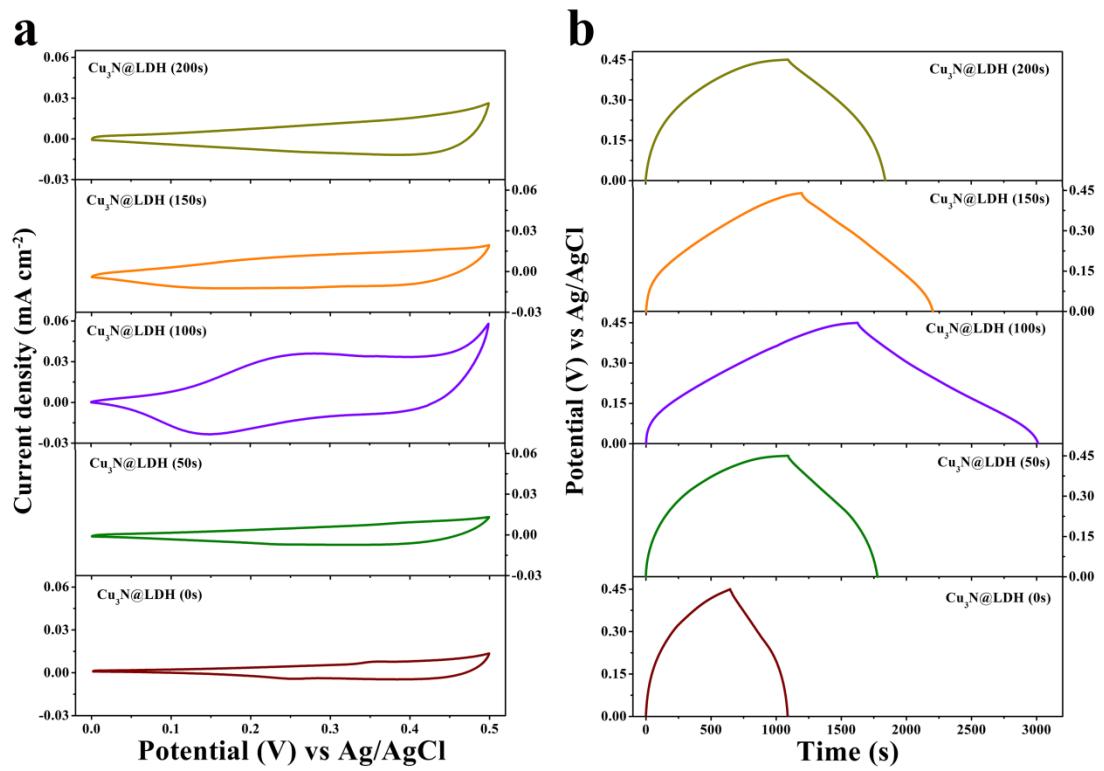


Fig. S5 (a) CVs curves at a scan rate of 5 mV s^{-1} and (b) the corresponding GCD curves at 1 mA cm^{-2} for the $\text{Cu}_3\text{N}@\text{CoFe-LDH}$ (LDH deposition time: 0, 25, 50, and 100 s) in 2 M KOH solution.

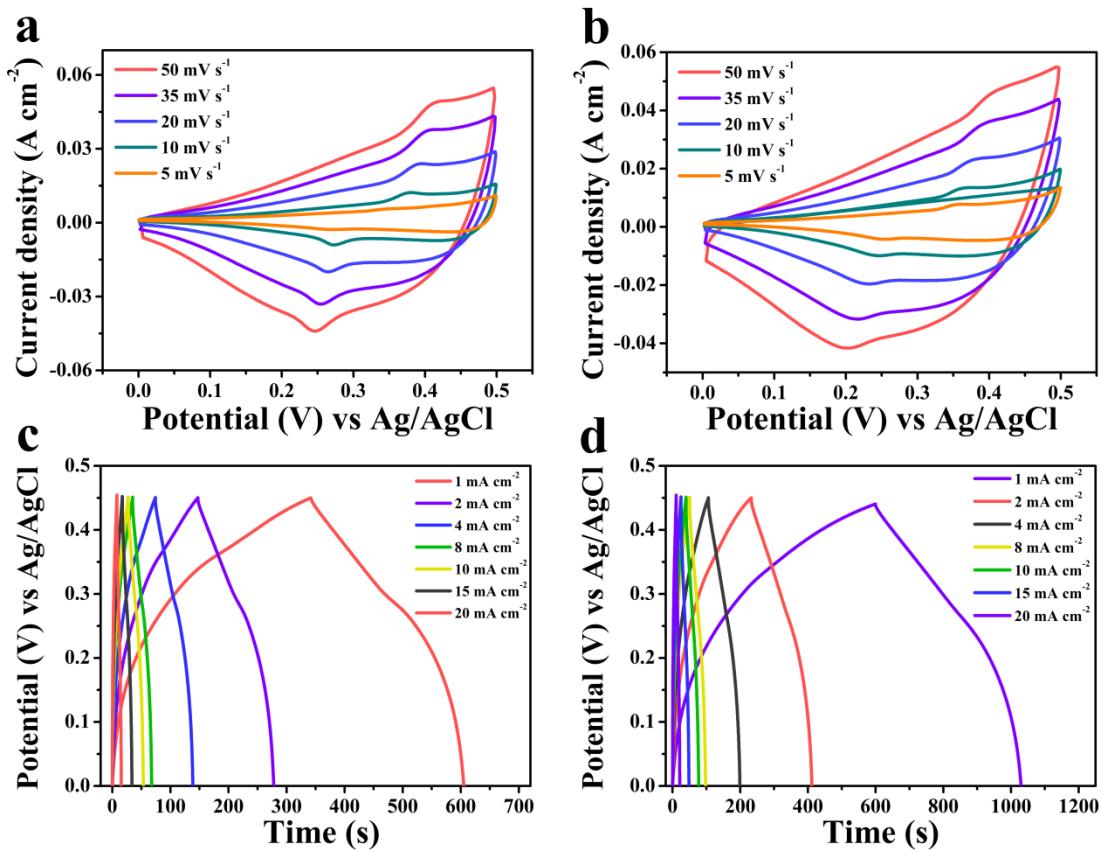


Fig. S6 CVs curves for the pristine CuO (a) and Cu₃N (b) NWAs in 2 M KOH solution at various scan rates; (c,d) The corresponding GCD curves for the two samples at various current densities.

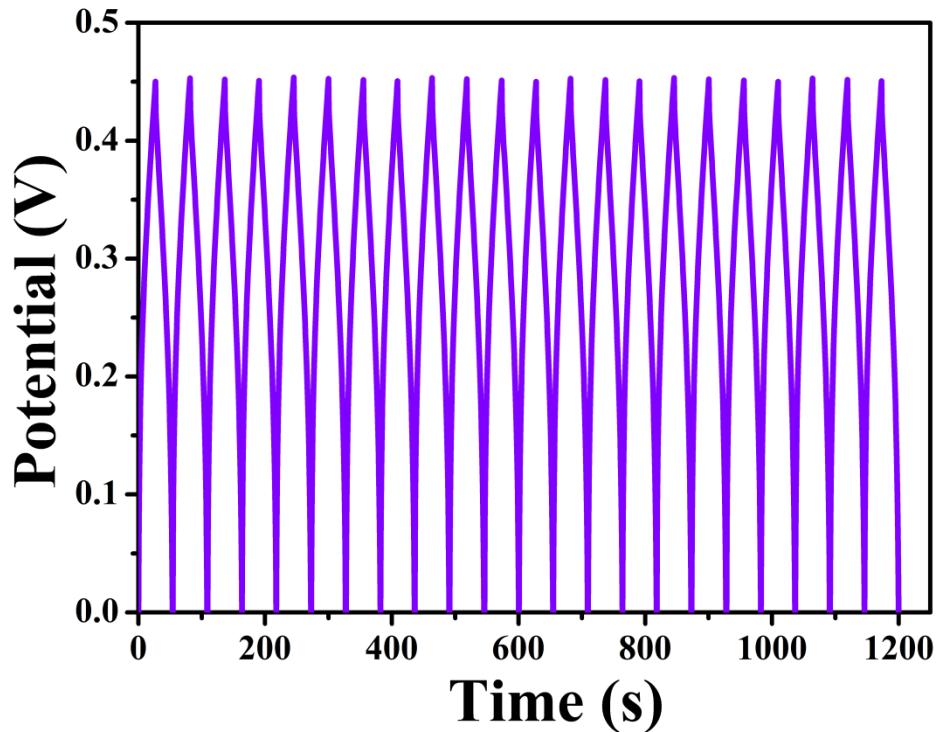


Fig. S7 GCD results of the last 20 cycles for Cu₃N@CoFe-LDH in 10000 cycles.

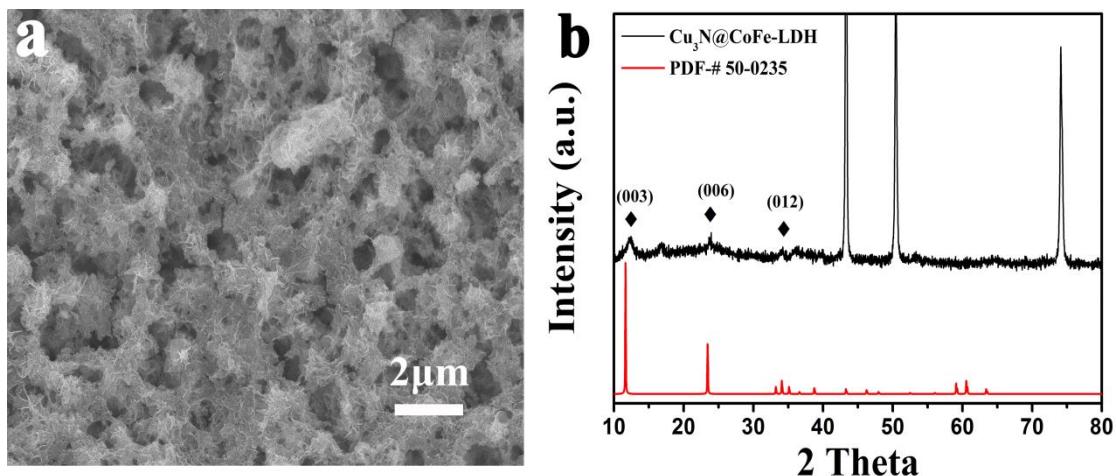


Fig. S8 SEM image (a) and XRD spectrum (b) of Cu_3N @CoFe-LDH NWAs electrode after 10000 cycles

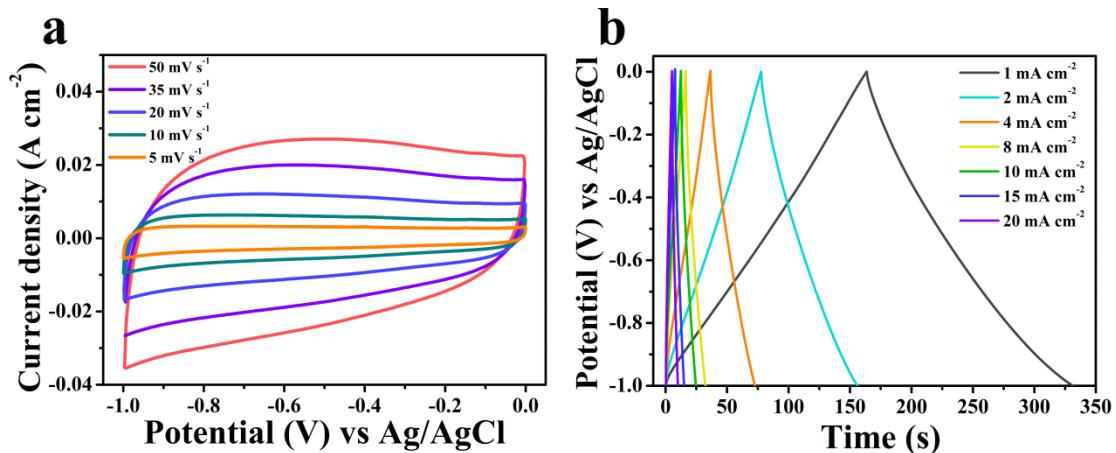


Fig. S9 CVs curves for the AC electrode (a) at various scan rates and The corresponding GCD curves (b) at various current densities in 2 M KOH solution.

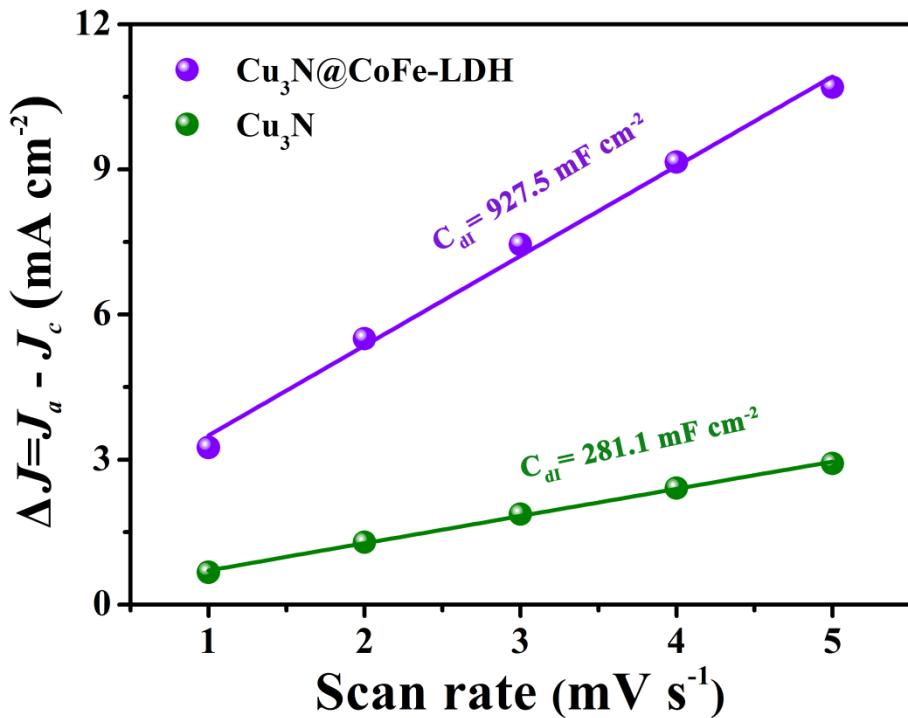


Fig. S10 Charging current density differences ($\Delta j = j_a - j_c$) plotted against scan rates of $\text{Cu}_3\text{N}@\text{CoFe-LDH}$ NWAs electrode. The linear slope is equivalent to twice of the double-layer capacitance C_{dl} .

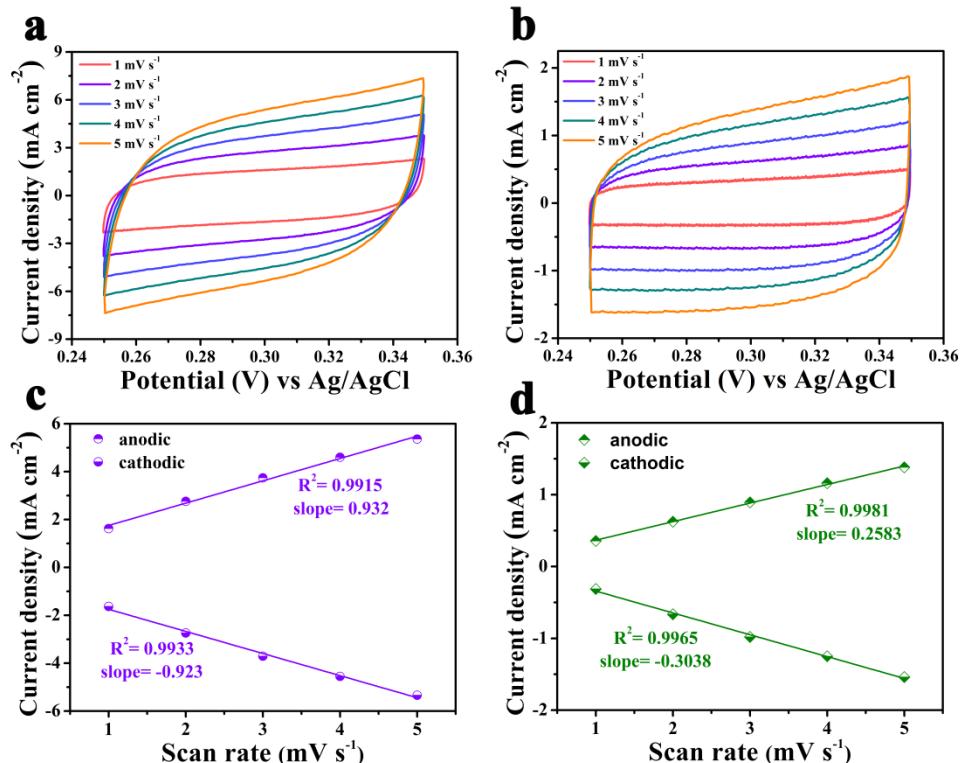


Fig. S11 CV curves at different scan rates (1, 2, 3, 4 and 5 mV s⁻¹) in a potential window where no Faradaic processes occur (0.25 - 0.35 V vs. Ag/AgCl) for $\text{Cu}_3\text{N}@\text{CoFe-LDH}$ NWAs electrode.⁵⁷

References

- S1 Z. H. Li, M. F. Shao, L. Zhou, R. K. Zhang, C. Zhang, J. B. Han, M. Wei, D. G. Evans and X. Duan, *Nano Energy*, 2016, **20**, 294.
- S2 Y. Zhang, H. Liu, M. Huang, J. M. Zhang, W. Zhang, F. Dong and Y. X. Zhang, *Chemelectrochem*, 2017, **4**, 721.
- S3 K. Y. Ma, F. Liu, M. B. Zhang, X. B. Zhang and J. P. Cheng, *Electrochimica Acta*, 2017, **225**, 425.
- S4 L. Yu, G. Q. Zhang, C. Z. Yuan and X. W. (D.) Lou, *Chem. Commun.*, 2013, **49** , 137.
- S5 X. H. Xia, J. P. Tu, Y. Q. Zhang, X. L. Wang, C. D. Gu, X. B. Zhao and H. J. Fan, *ACS Nano*, 2012, **6**, 5531.
- S6 L. Huang, D. C. Chen, Y. Ding, S. Feng, Z. L. Wang and M. L. Liu, *Nano Lett.*, 2013, **13**, 3135.
- S7 X. T. Han, C. Yu, J. Yang, C. T. Zhao, H. W. Huang, Z. B. Liu, P. M. Ajayan and J. S. Qiu, *Adv. Mater. Interfaces*, 2016, **3**, 1500782